

3A, 200V - 600V High Efficient Surface Mount Rectifier

FEATURES

- Very low profile, typical height of 1.1mm
- Excellent high temperature stability
- Glass passivated chip junction
- Controlled avalanche characteristics
- Low leakage current
- High forward surge capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- DC to DC converter
- · Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: TO-277A (SMPC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 0.095g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _F	3	Α			
V_{RRM}	200 - 600	V			
I _{FSM}	50	Α			
T_{JMAX}	175	°C			
Package	TO-277A (SMPC)				
Configuration	Single	die			

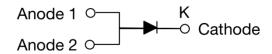








TO-277A (SMPC)



PARAMETER	SYMBOL	TPAU3D	TPAU3G	TPAU3J	UNIT	
Marking code on the device			AU3D	AU3G	AU3J	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	V	
Forward current	I _F	3		Α		
Surge peak forward current, 8.3m sine wave superimposed on rated	I _{FSM}	50		Α		
Non-repetitive avalanche energy $\frac{I_{AS} = 2.5 A \text{ Max}}{I_{AS} = 1.0 A \text{ Typ}}$		20			mJ	
		E _{AS}	30			mJ
Junction temperature	TJ	-55 to +175		°C		
Storage temperature	T _{STG}	-55 to +175		°C		

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance ⁽¹⁾	R _{eJL}	6	°C/W			
Junction-to-ambient thermal resistance ⁽²⁾	R _{eJA}	78	°C/W			

Notes:

- 1. Mounted on FR4 PCB with 16mm x 16mm Cu pad area
- 2. Free air, mounted on recommended pad

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Forward voltage ⁽¹⁾	$I_F = 3A, T_J = 25^{\circ}C$	V	1.50	1.88	V	
Forward voltage	I _F = 3A, T _J = 125°C	V _F	1.10	1.35	V	
Reverse current @ rated V _B ⁽²⁾	T _J = 25°C		-	10	μΑ	
Reverse current @ rated V _R	T _J = 125°C	I _R	-	250	μΑ	
Junction capacitance	1MHz, V _R = 4.0V	CJ	60	-	pF	
Reverse recovery time	IF = 0.5A, IR = 1.0A Irr = 0.25A	t _{rr}	-	75	ns	

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
TPAU3x	TO-277A (SMPC)	6,000 / Tape & Reel			

Notes:

1. "x" defines voltage from 200V(TPAU3D) to 600V(TPAU3J)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

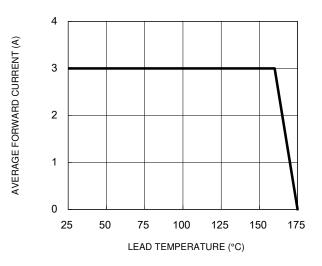


Fig.3 Typical Reverse Characteristics

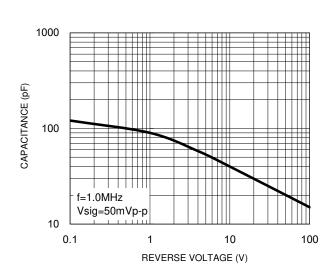
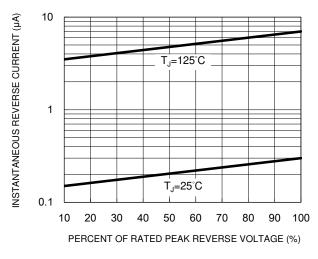


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



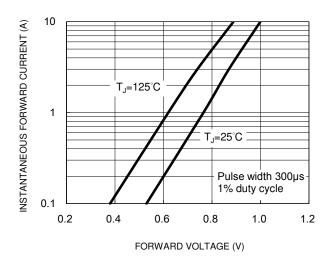
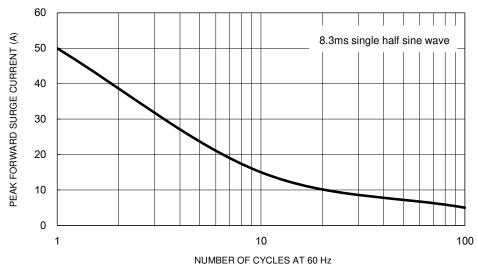


Fig.5 Maximum Non-Repetitive Forward Surge Current



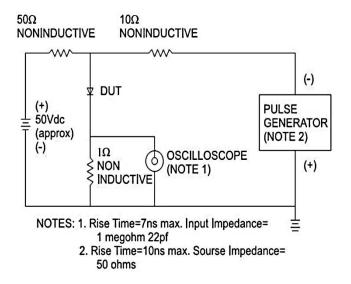
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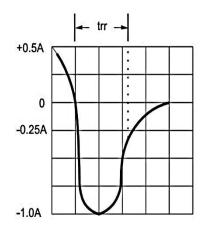


CHARACTERISTICS CURVES

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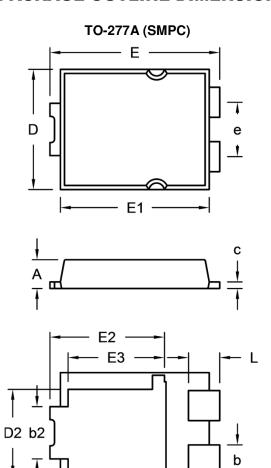
Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram





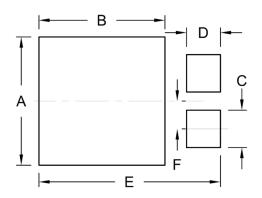


PACKAGE OUTLINE DIMENSIONS



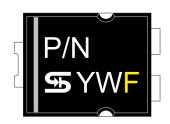
DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min.	Max.	Min.	Max.	
Α	1.000	1.200	0.039	0.047	
b	1.000	1.300	0.039	0.051	
b2	1.850	2.150	0.073	0.085	
С	0.175	0.325	0.007	0.013	
D	4.550	4.650	0.179	0.183	
D2	3.170	3.470	0.125	0.137	
E	6.350	6.650	0.250	0.262	
E1	5.650	5.750	0.222	0.226	
E2	4.235	4.535	0.167	0.179	
E3	3.540	3.840	0.139	0.151	
е	1.930	2.230	0.076	0.088	
L	1.043	1.343	0.041	0.053	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	4.80	0.189
В	4.72	0.186
С	1.40	0.055
D	1.27	0.050
Е	6.80	0.268
F	1.04	0.041

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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